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# PRE-RELEASE VERSION (FDIS)



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**Field device tool (FDT) interface specification –  
Part 302: Communication profile integration – IEC 61784 CPF 2**

INTERNATIONAL  
ELECTROTECHNICAL  
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TITLE:

**Field device tool (FDT) interface specification - Part 302: Communication profile integration - IEC 61784 CPF 2**

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

### FIELD DEVICE TOOL (FDT) INTERFACE SPECIFICATION –

#### Part 302: Communication profile integration – IEC 61784 CPF 2

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IEC 62453-302 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation. It is an International Standard.

This third edition cancels and replaces the second edition published in 2016. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) improved support for Ethernet IP (see 9.3, Clause 10, and 12.4).

Each part of the IEC 62453-3xy series is intended to be read in conjunction with IEC 62453-2.

The text of this International Standard is based on the following documents:

Draft	Report on voting
65E/XX/FDIS	65E/XX/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at [www.iec.ch/members\\_experts/refdocs](http://www.iec.ch/members_experts/refdocs). The main document types developed by IEC are described in greater detail at [www.iec.ch/standardsdev/publications](http://www.iec.ch/standardsdev/publications).

A list of all parts of the IEC 62453 series, under the general title *Field Device Tool (FDT) interface specification*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under [webstore.iec.ch](http://webstore.iec.ch) in the data related to the specific document. At this date, the document will be

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- withdrawn,
- replaced by a revised edition, or
- amended.

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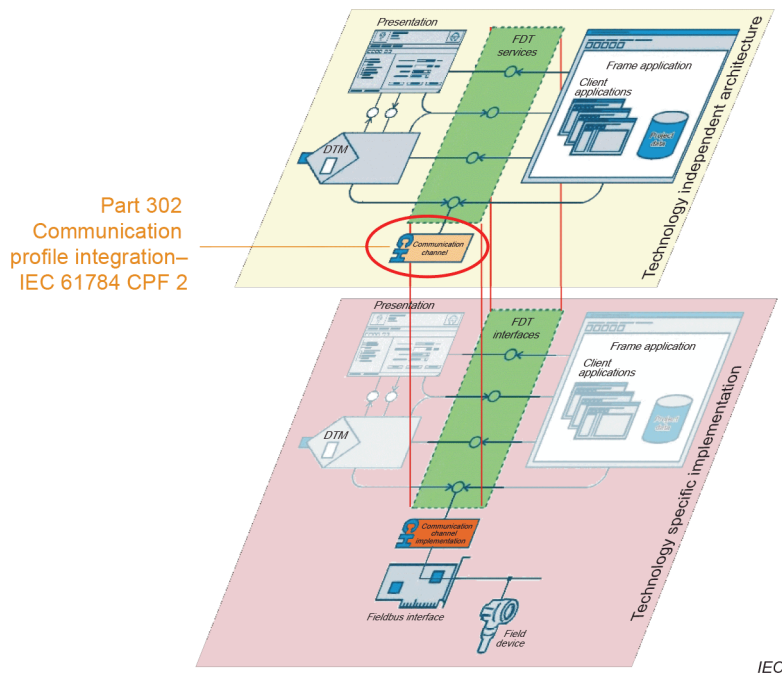
## INTRODUCTION

This part of IEC 62453 is an interface specification for developers of FDT (Field Device Tool) components for function control and data access within a client/server architecture. The specification is a result of an analysis and design process to develop standard interfaces to facilitate the development of servers and clients by multiple vendors that need to interoperate seamlessly.

With the integration of fieldbuses into control systems, there are a few other tasks which need to be performed. In addition to fieldbus- and device-specific tools, there is a need to integrate these tools into higher-level system-wide planning or engineering tools. In particular, for use in extensive and heterogeneous control systems, typically in the area of the process industry, the unambiguous definition of engineering interfaces that are easy to use for all those involved is of great importance.

A device-specific software component, called DTM (Device Type Manager), is supplied by the field device manufacturer with its device. The DTM is integrated into engineering tools via the FDT interfaces defined in this specification. The approach to integration is in general open for all kinds of fieldbuses and thus meets the requirements for integrating different kinds of devices into heterogeneous control systems.

Figure 1 shows how IEC 62453-302 is aligned in the structure of the IEC 62453 series [1].



**Figure 1 – Part 302 of the IEC 62453 series**

NOTE For an example for the technology specific implementation of this document, see [2].

## FIELD DEVICE TOOL (FDT) INTERFACE SPECIFICATION –

### Part 302: Communication profile integration – IEC 61784 CPF 2

#### 1 Scope

This part of IEC 62453 provides information for integrating the CIP™ technology into the FDT interface specification (IEC 62453-2). Communication Profile Family 2 (commonly known as CIP™<sup>1</sup>) defines communication profiles based on IEC 61158-2 Type 2, IEC 61158-3-2, IEC 61158-4-2, IEC 61158-5-2, IEC 61158-6-2, and IEC 62026-3. The basic profiles CP 2/1 (ControlNet™<sup>2</sup>), CP 2/2 (EtherNet/IP™<sup>3</sup>), and CP 2/3 (DeviceNet™<sup>1</sup>) are defined in IEC 61784-1 and IEC 61784-2. An additional communication profile (CompoNet™<sup>1</sup>), also based on CIP™, is defined in IEC 62026-7.

This part of IEC 62453 specifies communication and other services.

This specification neither contains the FDT specification nor modifies it.

#### 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61158-2, *Industrial communication networks – Fieldbus specifications – Part 2: Physical layer specification and service definition*

IEC 61158-3-2<sup>4</sup>, *Industrial communication networks – Fieldbus specifications – Part 3-2: Data-link layer service definition – Type 2 elements*

IEC 61158-4-2, *Industrial communication networks – Fieldbus specifications – Part 4-2: Data-link layer protocol specification – Type 2 elements*

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<sup>1</sup> CIP™ (Common Industrial Protocol), DeviceNet™ and CompoNet™ are trade names of Open DeviceNet Vendor Association, Inc (ODVA). This information is given for the convenience of users of this document and does not constitute an endorsement by IEC of the trade name holder or any of its products. Compliance to this standard does not require use of the trade names CIP™, DeviceNet™ or CompoNet™. Use of the trade names CIP™, DeviceNet™ or CompoNet™ requires permission of Open DeviceNet Vendor Association, Inc.

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<sup>4</sup> A consolidated version of this document exists, comprising the second edition (2014-08) [documents 65C/759/FDIS and 65C/769/RVD] and its amendment 1 (2019-04) [documents 65C/945/FDIS and 65C/954/RVD].



IEC 61158-5-2:2019, *Industrial communication networks – Fieldbus specifications – Part 5-2: Application layer service definition – Type 2 elements*

IEC 61158-6-2:2019, *Industrial communication networks – Fieldbus specifications – Part 6-2: Application layer protocol specification – Type 2 elements*

IEC 61784-1, *Industrial communication networks – Profiles – Part 1: Fieldbus profiles*

IEC 61784-2, *Industrial communication networks – Profiles – Part 2: Additional fieldbus profiles for real-time networks based on ISO/IEC/IEEE 8802-3*

IEC 61784-3-2:2021, *Industrial communication networks – Profiles – Part 3-2: Functional safety fieldbuses – Additional specifications for CPF 2*

IEC 62026-3, *Low-voltage switchgear and controlgear – Controller-device interfaces (CDIs) – Part 3: DeviceNet*

IEC 62026-7, *Low-voltage switchgear and controlgear – Controller-device interfaces (CDIs) – Part 7: CompoNet*

IEC 62453-1:–<sup>5</sup>, *Field device tool (FDT) interface specification – Part 1: Overview and guidance*

IEC 62453-2:2022, *Field device tool (FDT) interface specification – Part 2: Concepts and detailed description*

ISO 15745-2:2003, *Industrial automation systems and integration – Open systems application integration framework – Part 2: Reference description for ISO 11898-based control systems*

ISO 15745-3:2003, *Industrial automation systems and integration – Open systems application integration framework – Part 3: Reference description for IEC 61158-based control systems*

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<sup>5</sup> Under preparation. Stage at the time of publication: IEC/RPUB 62453-1:2022.  
To be published concurrently with this document.